DS07-12535-2E

8-bit Proprietary Microcontroller

CMOS

F²MC-8L MB89850R Series

MB89855R/P857/W857

■ DESCRIPTION

The MB89850R series has been developed as a general-purpose version of the F²MC*-8L family consisting of proprietary 8-bit, single-chip microcontrollers.

In addition to the F²MC-8L CPU core which can operate at low voltage but at high speed, the microcontrollers contain a variety of peripheral functions such as a timer unit, PWM timers, a UART, a serial interface, a 10-bit A/D converter, and an external interrupt.

The MB89850R series is applicable to a wide range of applications from consumer products to industrial equipment, including portable devices.

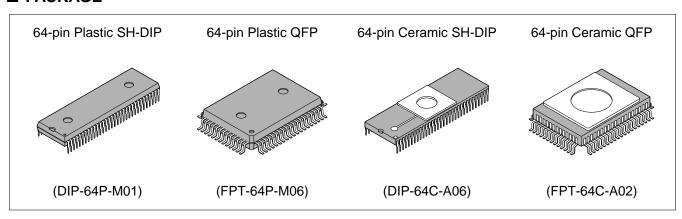
*: F2MC stands for FUJITSU Flexible Microcontroller.

■ FEATURES

- Various package options
 SDIP package (64 pins)/QFP package (64 pins)
- High-speed processing at low voltage
 Minimum execution time: 0.4 μs/3.5 V, 0.8 μs/2.7 V

(Continued)

■ PACKAGE



(Continued)

• F2MC-8L family CPU core

Instruction set optimized for controllers

Multiplication and division instructions 16-bit arithmetic operations Test and branch instructions Bit manipulation instructions, etc.

8-bit PWM timers: 2 channels
 Also usable as a reload timer

• UART

Full-duplex double buffer

Synchronous and asynchronous data transfer

• 8-bit serial I/O

Switchable transfer direction allows communication with various equipment.

• 10-bit A/D converter

Conversion time: 13.2 µs

Activation by an external input or a timer unit capable

• External interrupt: 4 channels

Four channels are independent and capable of wake-up from low-power consumption modes (with an edge detection function).

• Low-power consumption modes

Stop mode (Oscillation stops to minimize the current consumption.)

Sleep mode (The CPU stops to reduce the current consumption to approx. 1/3 of normal.)

· Bus interface functions

Including hold and ready functions

• Timer unit

Outputs non-overlap three-phase waveforms to control an AC inverter motor.

Also usable as a PWM timer (4 channels)

■ PRODUCT LINEUP

Parameter	MB89855R	MB89P857 MB89W857				
Classification	Mass production products (mask ROM products)	One-time PROM pruducts/EPROM products, also used for evaluation				
ROM size	16 K \times 8 bits (internal mask ROM)	$\begin{array}{c} 32~\text{K}\times8~\text{bits}\\ \text{(internal PROM, programming with}\\ \text{general-purpose EPROM programmer)} \end{array}$				
RAM size	512 × 8 bits	1 K × 8 bits				
CPU functions	Data bit length: 1, Minimum execution time: 0.4					
Ports	Output ports (N-ch open drain): 8 (Output ports (CMOS): 8 (All also serve as peripherals) All also serve as peripherals) All also serve as bus control pins) (All also serve as bus pins or peripherals)				
Timer unit	10-bit up/down count timer × 1 Compare registers with buffer × 4 Compare timer unit clear register with buffer × 1 Zero detection pin control 4 output channels Non-overlap three-phase waveform output Independent three-phase dead-time timer					
8-bit PWM timer 1, 8-bit PWM timer 2	8-bit reload timer operation (toggled output capable, operating clock cycle: 0.4 μs to 25.6 μs) 8-bit resolution PWM operation (conversion cycle: 102 μs to 6.528 ms)					
UART	8 bits Clock synchronous/asynchronous data transfer capable					
8-bit serial I/O	8 bits LSB first/MSB first selectability One clock selectable from four transfer clocks (one external shift clock, three internal shift clocks: 0.8 μs, 3.2 μs, 12.8 μs)					
10-bit A/D converter	10-bit resolution \times 8 channels A/D conversion time: 13.2 μ s Continous activation by a compare channel 0 in timer unit or an external activation capable					
External interrupt	4 independent channels (edge selection, interrupt vector, source flag) Rising edge/falling edge selectability. Used also for wake-up from stop/sleep mode. (Edge detection is also permitted in stop mode.)					
Standby modes	Sleep mode, stop mode					
Process	CMOS					
Operating voltage*	2.7 V to 6.0 V	2.7 V to 5.5 V				

^{*:} Varies with conditions such as the operating frequency. (See section "■ Electrical Characteristics.")

■ PACKAGE AND CORRESPONDING PRODUCTS

Package	MB89855R	MB89P857	MB89W857
DIP-64P-M01	0	0	×
DIP-64C-A06	×	×	0
FPT-64P-M06	0	0	×
FPT-64C-A02	×	×	0

○ : Available ×: Not available

Note: For more information about each package, see section "■ Package Dimensions."

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

Before evaluating using the OTPROM (one-time PROM) products (also used for evaluation), verify its differences from the product that will actually be used.

Take particular care on the following point:

• The stack area, etc., is set at the upper limit of the RAM.

2. Current Consumption

When operated at low speed, the product with an OTPROM or an EPROM will consume more current than the product with a mask ROM.

However, the current consumption in sleep/stop modes is the same.

3. Mask Options

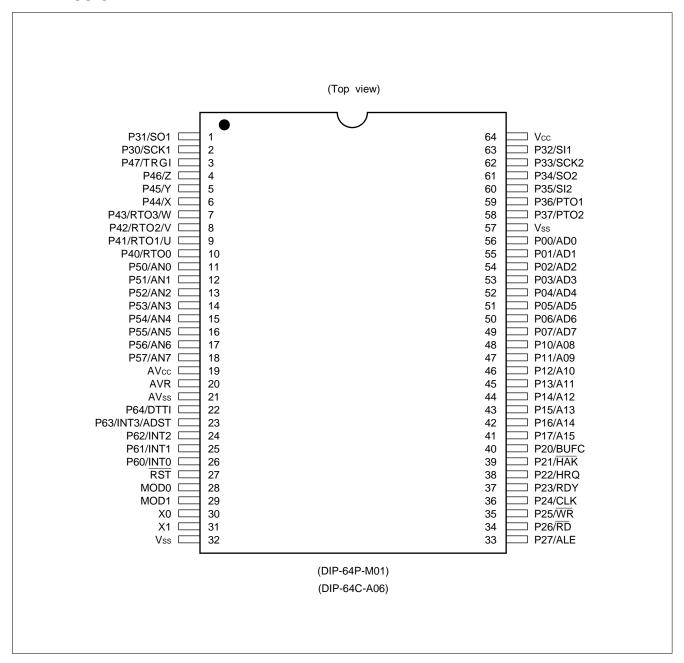
In the MB89P857/W857, no option can be set.

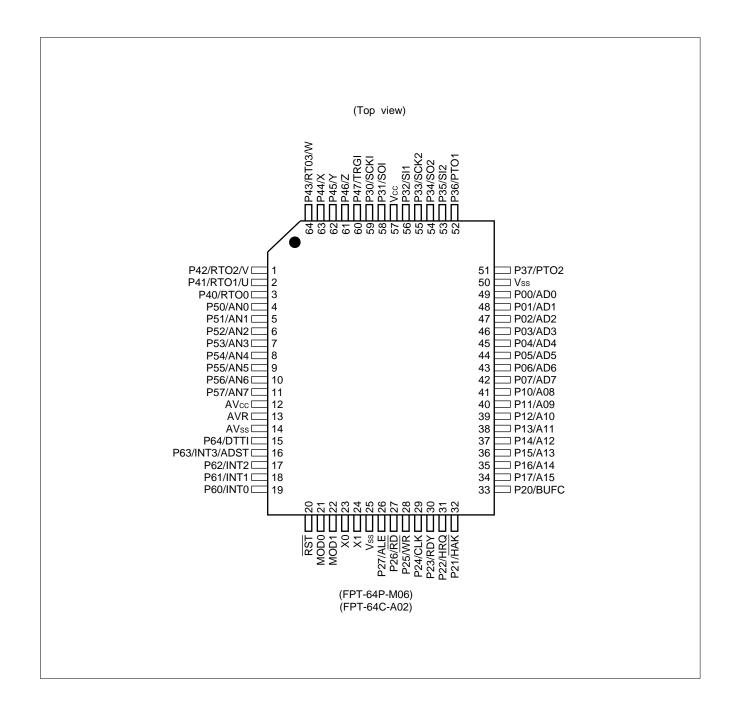
Before using options check section "■ Mask Options."

Take particular care on the following point:

• A pull-up resistor can be set for P00 to P07, P10 to P17 and P20 to P27 only at single-chip mode.

■ PIN ASSIGNMENT





■ PIN DESCRIPTION

Pin no.		Din name Circu			
SH-DIP*1	QFP*2	Pin name	type	Function	
30	23	X0	А	Crystal oscillator pins (10 MHz)	
31	24	X1			
28	21	MOD0	В	Operating mode selection pins	
29	22	MOD1		Connect directly to Vcc or Vss.	
27	20	RST	С	Reset I/O pin This pin is an N-ch open-drain output type with a pull-up resistor, and a hysteresis input type. "L" is output from this pin by an internal reset source. The internal circuit is initialized by the input of "L".	
56 to 49	49 to 42	P00/AD0 to P07/AD7	D	General-purpose I/O ports When an external bus is used, these ports function as multiplex pins of lower address output and data I/O.	
48 to 41	41 to 34	P10/A08 to P17/A15	D	General-purpose I/O ports When an external bus is used, these ports function as upper address output.	
40	33	P20/BUFC	F	General-purpose output port When an external bus is used, this port can also be use as a buffer control output.	
39	32	P21/HAK	F	General-purpose output port When an external bus is used, this port can also be used as a hold acknowledge output.	
38	31	P22/HRQ	D	General-purpose output port When an external bus is used, this port can also be use as a hold request input.	
37	30	P23/RDY	D	General-purpose output port When an external bus is used, this port functions as a ready input.	
36	29	P24/CLK	F	General-purpose output port When an external bus is used, this port functions as a clock output.	
35	28	P25/WR	F	General-purpose output port When an external bus is used, this port functions as a write signal output.	
34	27	P26/RD	F	General-purpose output port When an external bus is used, this port functions as a read signal output.	
33	26	P27/ALE	F	General-purpose output port When an external bus is used, this port functions as an address latch signal output.	
2	59	P30/SCK1	Е	General-purpose I/O port Also serves as the clock I/O for the UART. This port is a hysteresis input type.	

^{*1:} DIP-64P-M01, DIP-64C-A06

^{*2:} FPT-64P-M06, FPT-64C-A02

Pin	no.	Din name	Circuit	Eunotion	
SH-DIP*1	QFP*2	Pin name	type	Function	
1	58	P31/SO1	E	General-purpose I/O port Also serves as the data output for the UART. This port is a hysteresis input type.	
63	56	P32/SI1	E	General-purpose I/O port Also serves as the data input for the UART. This port is a hysteresis input type.	
62	55	P33/SCK2	E	General-purpose I/O port Also serves as the clock I/O for the 8-bit serial I/O. This port is a hysteresis input type.	
61	54	P34/SO2	E	General-purpose I/O port Also serves as the data output for the 8-bit serial I/O. This port is a hysteresis input type.	
60	53	P35/SI2	E	General-purpose I/O port Also serves as the data input for the 8-bit serial I/O. This port is a hysteresis input type.	
59	52	P36/PTO1	Е	General-purpose I/O port Also serves as the pulse output for the 8-bit PWM timer 1 This port is a hysteresis input type.	
58	51	P37/PTO2	Е	General-purpose I/O port Also serves as the pulse output for the 8-bit PWM timer 2 This port is a hysteresis input type.	
10	3	P40/RTO0	Е	General-purpose I/O port Also serves as the pulse output for the timer unit. This port is a hystereisis input type.	
9, 8, 7	2, 1, 64	P41/RTO1/U, P42/RTO2/V, P43/RTO3/W	Е	General-purpose I/O ports Also serve as the pulse output or non-overlap three- phase waveform output for the timer unit. These ports are a hysteresis input type.	
6, 5, 4	63, 62, 61	P44/X, P45/Y, P46/Z	E	General-purpose I/O ports Also serve as a non-overlap three-phase waveform output. These ports are a hysteresis input type.	
3	60	P47/TRGI	E	General-purpose I/O port Also serves as the trigger input for the timer unit. This port is a hysteresis input type.	
11 to 18	4 to 11	P50/AN0 to P57/AN7	G	N-ch open-drain output ports Also serve as the analog input for the A/D converter.	
26 to 24	19 to 17	P60/INT0 to P62/INT2	Н	General-purpose input ports Also serve as an external interrupt input. These ports are a hysteresis input type.	
23	16	P63/INT3/ ADST	Н	General-purpose input port Also serves as an external interrupt input and as the activation trigger input for the A/D converter. This port is a hysteresis input type.	

^{*1:} DIP-64P-M01, DIP-64C-A06

^{*2:} FPT-64P-M06, FPT-64C-A02

Pin	no.	Pin name Circuit		Function		
SH-DIP*1	QFP*2	Pinname	type	Function		
22	15	P64/DTTI	Н	General-purpose input port Also serves as a dead-time timer disable input. This port is a hysteresis input type. DTTI input is with a noise canceller.		
64	57	Vcc	_	Power supply pin		
32, 57	25, 50	Vss	_	Power supply (GND) pins		
19	12	AVcc	_	A/D converter power supply pin		
20	13	AVR	_	A/D converter reference voltage input pin		
21	14	AVss	_	A/D converter power supply (GND) pin Use this pin at the same voltage as Vss.		

^{*1:} DIP-64P-M01, DIP-64C-A06

^{*2:} FPT-64P-M06, FPT-64C-A02

■ I/O CIRCUIT TYPE

Туре	Circuit	Remarks
A	Standby control signal	At an oscillation feedback resistor of approximately 1 MΩ/5.0 V
В		
С	R R N-ch	 At an output pull-up resistor (P-ch) of approximately 50 kΩ/5.0 V Hysteresis input
D	P-ch P-ch N-ch	 CMOS output CMOS input Pull-up resistor optional (Mask ROM products) At a pull-up resistor of approximately 50 kΩ/5.0 V
E	P-ch N-ch N-ch	 CMOS output Hysteresis input Pull-up resistor optional (Mask ROM products) At a pull-up resistor of approximately 50 kΩ/5.0 V

Туре	Circuit	Remarks
F	P-ch N-ch	 CMOS output Pull-up resistor optional (Mask ROM products) At a pull-up resistor of approximately 50 kΩ/5.0 V
G	N-ch Analog input	N-ch open-drain output Analog input
Н	R D	 Hysteresis input Pull-up resistor optional (Mask ROM products) At a pull-up resistor of approximately 50 kΩ/5.0 V

■ HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than V_{CC} or lower than V_{SS} is applied to input and output pins other than medium- and high-voltage pins or if higher than the voltage which shows on "1. Absolute Maximum Ratings" in section "■ Electrical Characteristics" is applied between V_{CC} and V_{SS}.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also, take care to prevent the analog power supply (AVcc and AVR) and analog input from exceeding the digital power supply (Vcc) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D and D/A Converters

Connect to be AVcc = DAVC = Vcc and AVss = AVR = Vss even if the A/D and D/A converters are not in use.

4. Treatment of N.C. Pin

Be sure to leave (internally connected) N.C. pin open.

5. Power Supply Voltage Fluctuations

Although $V_{\rm CC}$ power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that $V_{\rm CC}$ ripple fluctuations (P-P value) will be less than 10% of the standard $V_{\rm CC}$ value at the commercial frequency (50 to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

Even when an external clock is used, oscillation stabilization time is required for power-on reset (optional) and wake-up from stop mode.

■ PROGRAMMING TO THE EPROM ON THE MB89P857/W857

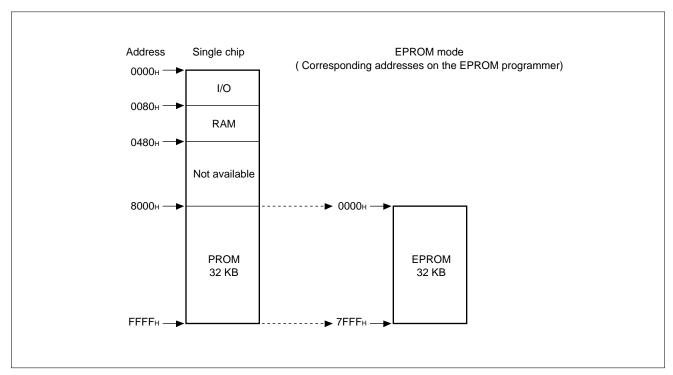
The MB89P857/W857 are an OTPROM version of the MB89850R series.

1. Features

- 32-Kbyte PROM on chip
- Equivalency to the MBM27C256A in EPROM mode (when programmed with the EPROM programmer)

2. Memory Space

Memory space in EPROM mode is diagrammed below.



3. Programming to the EPROM

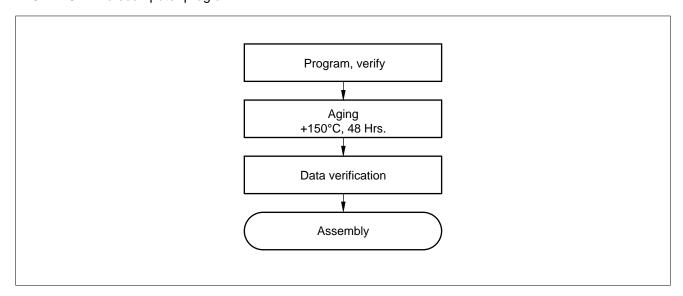
In EPROM mode, the MB89P857/W857 functions equivalent to the MBM27C256A. This allows the PROM to be programmed with a general-purpose EPROM programmer (the electronic signature mode cannot be used) by using the dedicated socket adapter.

· Programming procedure

- (1) Set the EPROM programmer to the MBM27C256A.
- (2) Load program data into the EPROM programmer at 0000_H to 7FFF_H (note that addresses 8000_H to FFFF_H while operating as a single chip assign to addresses 0000_H to 7FFF_H in EPROM mode.)
- (3) Program to 0000H to 7FFFH with the EPROM programmer.

4. Recommended Screening Conditions

High-temperature aging is recommended as the pre-assembly screening procedure for a product with a blanked OTPROM microcomputer program.



5. Programming Yield

All bits cannot be programmed at Fujitsu shipping test to a blanked OTPROM microcomputer, due to its nature. For this reason, a programming yield of 100% cannot be assured at all times.

6. Erasure

In order to clear all locations of their programmed contents, it is necessary to expose the internal EPROM to an ultraviolet light source. A dosage of 10 W-seconds/cm² is required to completely erase an internal EPROM. This dosage can be obtained by exposure to an ultraviolet lamp (wavelength of 2537 Angstroms (Å)) with intensity of 12000 μ W/cm² for 15 to 21 minutes. The internal EPROM should be about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the internal EPROM and similar devices, will erase with light sources having wavelengths shorter than 4000 Å. Although erasure time will be much longer than with UV source at 2537 Å, nevertheless the exposure to fluorescent light and sunlight will eventually erase the internal EPROM, and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package windows should be covered by an opaque label or substance.

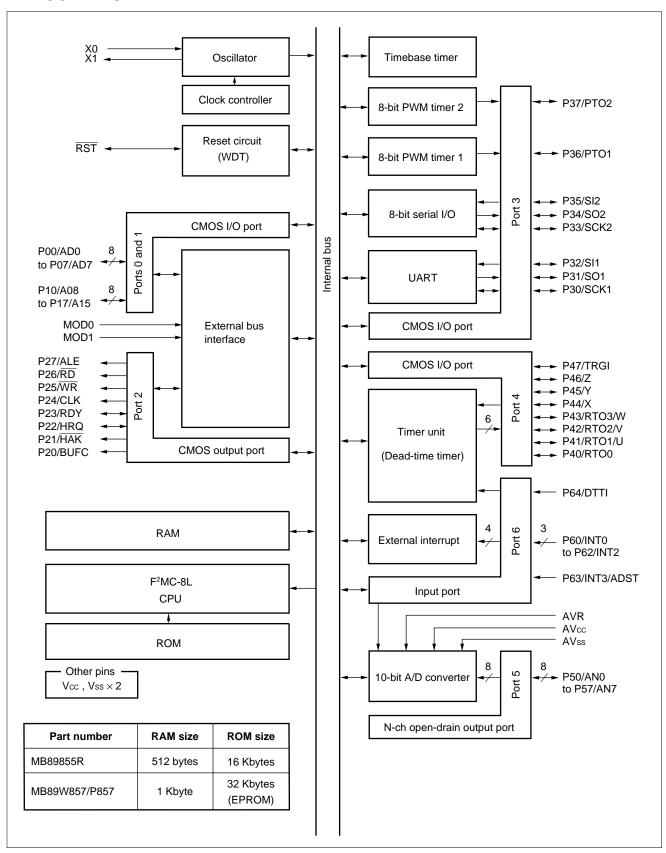
7. EPROM Programmer Socket Adapter

Package	Compatible socket adapter		
DIP-64P-M01	ROM-64SD-28DP-8L*		
FPT-64P-M06	ROM-64QF-28DP-8L		
FPT-64P-A02	ROM-64QF-28DP-8L5		

^{*:} Connect the adapter jumper pin to Vss when using.

Inquiry: Sun Hayato Co., Ltd.: Fax 81-3-5396-9106

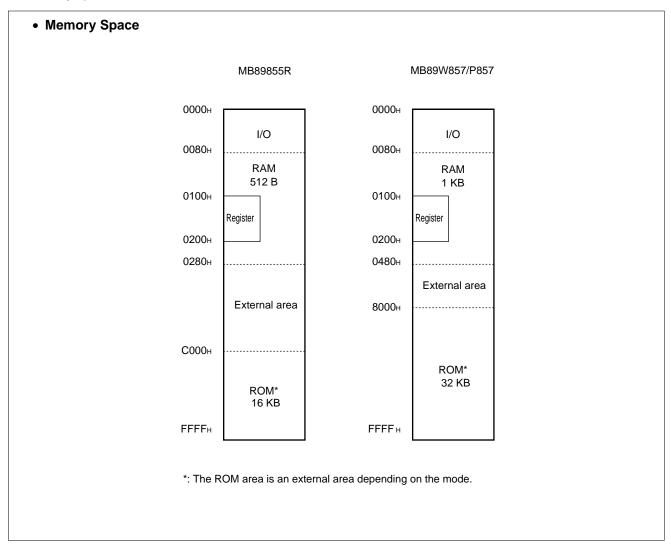
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Space

The microcontrollers of the MB89850R series offer a memory space of 64 Kbytes for storing all of I/O, data, and program areas. The I/O area is located at the lowest address. The data area is provided immediately above the I/O area. The data area can be divided into register, stack, and direct areas according to the application. The program area is located at exactly the opposite end, that is, near the highest address. Provide the tables of interrupt reset vectors and vector call instructions toward the highest address within the program area. The memory space of the MB89860/850 series is structured as illustrated below.



2. Registers

The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following dedicated registers are provided:

Program counter (PC): A 16-bit register for indicating instruction storage positions

Accumulator (A): A 16-bit temporary register for storing arithmetic operations, etc. When the

instruction is an 8-bit data processing instruction, the lower byte is used.

Temporary accumulator (T): A 16-bit register which performs arithmetic operations with the accumulator

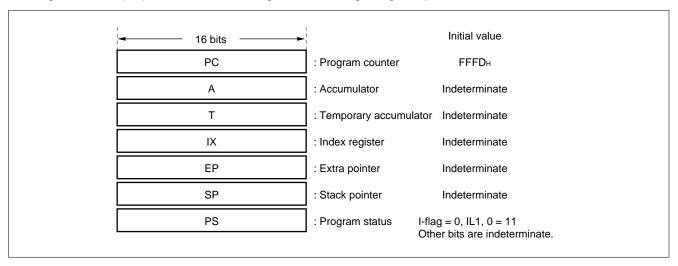
When the instruction is an 8-bit data processing instruction, the lower byte is used.

Index register (IX): A 16-bit register for index modification

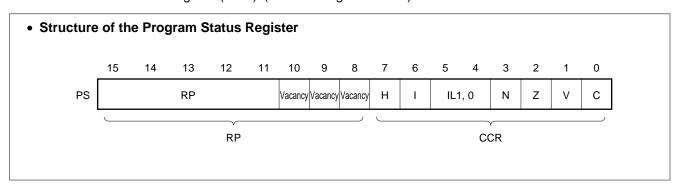
Extra pointer (EP): A 16-bit pointer for indicating a memory address

Stack pointer (SP): A 16-bit register for indicating a stack area

Program status (PS): A 16-bit register for storing a register pointer, a condition code

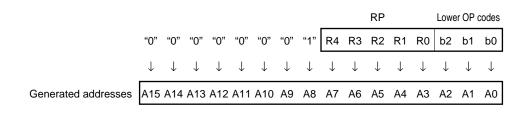


The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)



The RP indicates the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule illustrated below.

• Rule for Conversion of Actual Addresses of the General-purpose Register Area



The CCR consists of bits indicating the results of arithmetic operations and the contents of transfer data and bits for control of CPU operations at the time of an interrupt.

H-flag: Set when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared otherwise. This flag is for decimal adjustment instructions.

I-flag: Interrupt is allowed when this flag is set to 1. Interrupt is prohibited when the flag is set to 0. Set to 0 when reset.

IL1, 0: Indicates the level of the interrupt currently allowed. Processes an interrupt only if its request level is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	High-low
0	0	1	High
0	1	l	†
1	0	2	
1	1	3	Low = no interrupt

N-flag: Set if the MSB is set to 1 as the result of an arithmetic operation. Cleared when the bit is set to 0.

Z-flag: Set when an arithmetic operation results in 0. Cleared otherwise.

V-flag: Set if the complement on 2 overflows as a result of an arithmetic operation. Reset if the overflow does not occur.

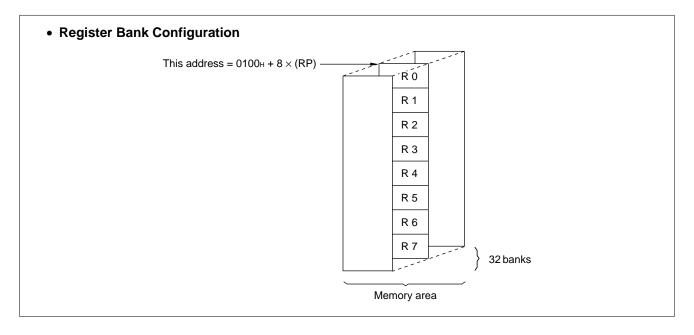
C-flag: Set when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: An 8-bit register for storing data

The general-purpose registers are 8 bits and located in the register banks of the memory. One bank contains eight registers and up to a total of 32 banks can be used on the MB89850R series. The bank currently in use is indicated by the register bank pointer (RP).

Note: The number of register banks that can be used varies with the RAM size.



■ I/O MAP

Address	Read/write	Register name	Register description	
00н	(R/W)	PDR0	Port 0 data register	
01н	(W)	DDR0	Port 0 data direction register	
02н	(R/W)	PDR1	Port 1 data register	
03н	(W)	DDR1	Port 1 data direction register	
04н	(R/W)	PDR2	Port 2 data register	
05н	(W)	BCTR	External bus pin control register	
06н			Vacancy	
07н			Vacancy	
08н	(R/W)	STBC	Standby control register	
09н	(W)	WDTC	Watchdog timer control register	
0Ан	(R/W)	TBTC	Timebase timer control register	
0Вн			Vacancy	
0Сн	(R/W)	PDR3	Port 3 data register	
0Dн	(W)	DDR3	Port 3 data direction register	
0Ен	(R/W)	PDR4	Port 4 data register	
0Fн	(W)	DDR4	Port 4 data direction register	
10н	(R/W)	PDR5	Port 5 data register	
11н			Vacancy	
12н	(R)	PDR6	Port 6 data register	
13н			Vacancy	
14н	(R/W)	PDR7	Port 7 data register	
15н			Vacancy	
16н	(R/W)	PDR8	Port 8 data register	
17н to 1Bн			Vacancy	
1Сн	(R/W)	CTR1	PWM control register 1	
1Dн	(W)	CMR1	PWM compare register 1	
1Ен	(R/W)	CTR2	PWM control register 2	
1F _H	(W)	CMR2	PWM compare register 2	
20н	(R/W)	SMC	UART serial mode control register	
21н	(R/W)	SRC	UART serial rate control register	
22н	(R/W)	SSD	UART serial status/data register	
23н	(R/W)	SIDR/SODR	UART serial data register	
24н	(R/W)	SMR	Serial mode register	
25н	(R/W)	SDR	Serial data register	
			!	

(Continued)

Address	Read/write	Register name Register description	
26н	(R/W)	EIC1	External interrupt control register 1
27н	(R/W)	EIC2	External interrupt control register 2
28н	(R/W)	ADC1	A/D converter control register 1
29н	(R/W)	ADC2	A/D converter control register 2
2Ан	(R)	ADDH	A/D converter data register (H)
2Вн	(R)	ADDL	A/D converter data register (L)
2Сн			Vacancy
2Dн	(W)	ZOCTR	Zero detection output control register
2Ен	(W)	CLRBRH	Compare clear buffer register (H)
2Fн	(W)	CLRBRL	Compare clear buffer register (L)
30н	(R/W)	TCSR	Timer control status register
31н	(R/W)	CICR	Compare interrupt control register
32н	(R/W)	TMCR	Timer mode control register
33н	(R/W)	COER	Compare/port selection register
34н	(R/W)	CMCR	Compare buffer mode control register
35н	(R/W)	DTCR	Dead-time timer control register
36н	(W)	DTSR Dead-time setting register	
37н	(R/W)	OCTBR	Output control buffer register
38н	(W)	OCPBR0H	Output compare buffer register 0 (H)
39н	(W)	OCPBR0L	Output compare buffer register 0 (L)
ЗАн	(W)	OCPBR1H	Output compare buffer register 1 (H)
3Вн	(W)	OCPBR1L	Output compare buffer register 1 (L)
3Сн	(W)	OCPBR2H	Output compare buffer register 2 (H)
3Dн	(W)	OCPBR2L	Output compare buffer register 2 (L)
3Ен	(W)	OCPBR3H	Output compare buffer register 3 (H)
3Fн	(W)	OCPBR3L	Output compare buffer register 3 (L)
40н to 7Вн			Vacancy
7Сн	(W)	ILR1	Interrupt level setting register 1
7Dн	(W)	ILR2 Interrupt level setting register 2	
7Е н	(W)	ILR3 Interrupt level setting register 3	
7 Fн		1	Vacancy

Notes: • Do not use vacancies.

• When a read-modify-write instruction (such as bit set) is used to access a write-only register or a register containing a write-only bit, a bit designated by the instruction will have a predetermined value. However, a write-only bit included, if any, in bits not defined by the instruction will cause a malfunction. So no access to the register should be tried with any read-modefy-write instruction.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks
Farameter	Syllibol	Min.	Max.		
Power supply voltage	Vcc AVcc	Vss - 0.3	Vss + 7.0	V	*
A/D converter reference input voltage	AVR	Vss - 0.3	Vss + 7.0	V	AVR must not exceed AVcc + 0.3 V.
Program voltage	VPP	Vss - 0.3	13.0	V	MOD1 pins of MB89P857/ W857
Input voltage	Vı	Vss - 0.3	Vcc + 0.3	V	
Output voltage	Vo	Vss - 0.3	Vss + 0.3	V	
"L" level maximum output current	lol	_	20	mA	
"L" level average output current	loLAV1	_	4	mA	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P50 to P57
	lolav2	_	15	mA	P40 to P47
"L" level total average output current	∑lolav1	_	30	mA	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P50 to P57
	Σ lolav2	_	50	mA	P40 to P47
"H" level maximum output current	Іон	_	-20	mA	
"H" level average output current	І онаv	_	-4	mA	
"H" level total maximum output current	ΣІон	_	-20	mA	
Power consumption	Po	_	300	mW	
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	- 55	+150	°C	

^{*:} Use AVcc and Vcc set at the same voltage.

Take care so that AVcc does not exceed Vcc, such as when power is turned on.

WARNING: Permanent device damage may occur if the above "Absolute Maximum Ratings" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks		
raiametei	Symbol	Min.	Max.	Oille	Kemarks		
Power supply voltage		2.7*	6.0*	V	Normal operation assurance range* MB89855R		
	Vcc AVcc	2.7*	5.5*	V	Normal operation assurance range* MB89P857/W855		
		1.5	6.0	V	Retains the RAM state in stop mode		
A/D converter reference input voltage	AVR	0.0	AVcc	V			
Operating temperature	Та	-40	+85	°C			

^{*:} These values vary with the operating frequency, instruction cycle, and analog assurance range. See Figure 1 and "5. A/D Converter Electrical Characteristics."

Note: Connect the MOD0 and MOD1 pins to Vcc or Vss.

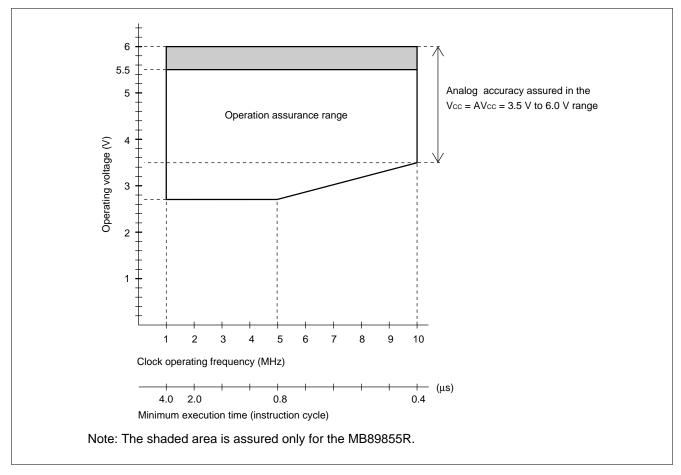


Figure 1 Operating Voltage vs. Clock Operating Frequency

3. DC Characteristics

 $(AVcc = Vcc = +5.0 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Danamatan	Courselle est	Din nome	O a maliti a m		Value		11	Remarks
Parameter	Symbol	Pin name	Condition	Min.	Тур.	Max.	Unit	Remarks
"H" level input voltage	Vін	P00 to P07, P10 to P17, P22, P23	_	0.7 Vcc	_	Vcc + 0.3	V	
H level lilput voltage	VIHS	RST, P30 to P37, P40 to P47, P60 to P64	_	0.8 Vcc	_	Vcc + 0.3	V	
"L" level input voltage	VIL	P00 to P07, P10 to P17, P22, P23	_	Vss - 0.3	_	0.3 Vcc	V	
L level iliput voltage	VILS	RST, P30 to P37, P40 to P47, P60 to P64	_	Vss - 0.3	_	0.2 Vcc	٧	
"H" level output voltage	Vон	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47	Iон = -2.0 mA	2.4	_	_	V	
"L" level output voltage	Vol	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P50 to P57	I _{OL} = +1.8 mA	_	_	0.4	V	
	V _{OL2}	P40 to P47	IoL = +1.5 mA	_	_	1.5	V	
Input leackage current	Іш	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P60 to P64, MOD0, MOD1	0.0 V < V1 < Vcc	_	_	±5	μΑ	
Pull-up resistance	RPULL	RST	V _I = 0.0 V	25	50	100	kΩ	With pull-up resistor
	Icc		Fc = 10 MHz Normal operation mode (External clock)	_	15	18	mA	
Power supply current	Iccs	Vcc	Fc = 10 MHz Sleep mode (External clock)	_	6	8	mA	
	Іссн		Stop mode T _A = +25°C	_	_	10	μΑ	
	IA	AVcc	Fc = 10 MHz, when A/D conversion is activated	_	6	_	μΑ	
Input capacitance	Cin	Other than AVcc, AVss, Vcc, and Vss	f = 1 MHz	_	10	_	pF	

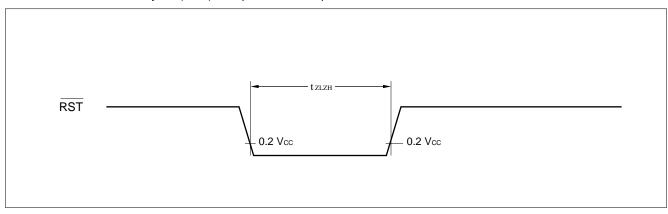
4. AC Characteristics

(1) Reset Timing

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, TA = -40°C to +85°C)$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks
	Syllibol	Condition	Min.	Max.	Oilit	Remarks
RST "L" pulse width	t zlzh	_	16 txcyL*		ns	

^{*:} txcyL is the oscillation cycle (1/Fc) to input to the X0 pin.



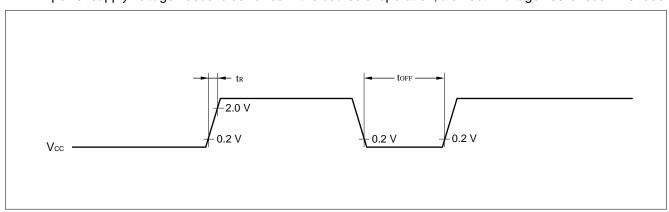
(2) Power-on Reset

$$(AVss = Vss = 0.0 V, TA = -40^{\circ}C to +85^{\circ}C)$$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks	
raidilietei	Symbol		Min.	Max.	Oille	i veniai ka	
Power supply rising time	t R		_	50	ms	Power-on reset function only	
Power supply cut-off time	toff	<u> </u>	1	_	ms	Due to repeated operations	

Note: Make sure that power supply rises within the selected oscillation stabilization time.

If power supply voltage needs to be varied in the course of operation, a smooth voltage rise is recommended.



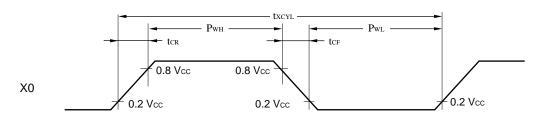
(3) Clock Timing

$$(AVss = Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$$

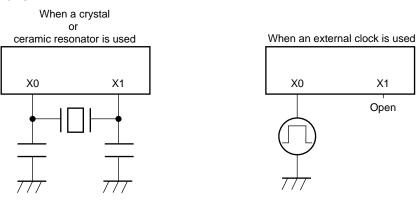
X1 Open

Parameter	Symbol	Pin name	Condition	Va	lue	Unit	Remarks
	Symbol	riii iiaiiie	Condition	Min.	Max.	Oilit	Remarks
Clock frequency	Fc	X0, X1		1	10	MHz	
Clock cycle time	txcyL			100	1000	ns	
Input clock pulse width	Pwh PwL	X0	<u> </u>	20	_	ns	External clock
Input clock rising/falling time	tcr tcr	, XU		_	10	ns	External clock

• X0 and X1 Timing Conditions



• Clock Conditions



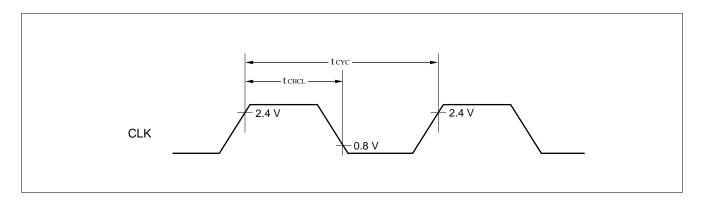
(4) Instruction Cycle

Parameter	Symbol	Value (typical)	Unit	Remarks
Instruction cycle (minimum execution time)	tinst	4/Fc	μs	$t_{inst} = 0.4 \mu s$ when operating at $F_C = 10 \text{ MHz}$

(5) Clock Output Timing

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin name	Condition	Va	lue	Unit	Remarks	
	Syllibol			Min.	Max.	Unit	Remarks	
Cycle time	tcyc	CLK	Load condition: 50 pF	200	_	ns	txcyL × 2 at 10 MHz oscillation	
$CLK \uparrow \to CLK \downarrow$	tchcl	OLK		30	100	ns	Approx. tcyc/2 at 10 MHz oscillation	

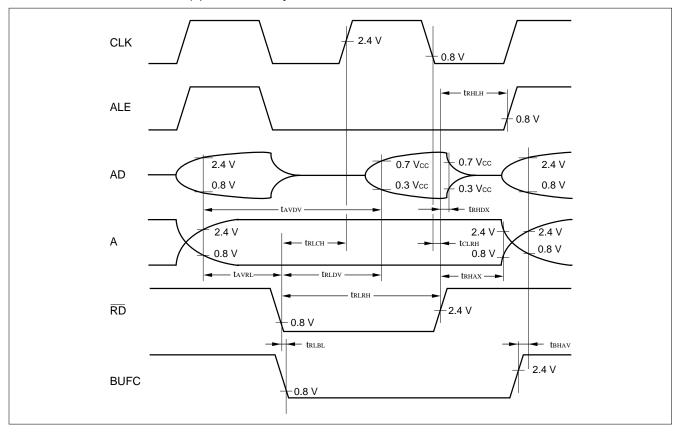


(6) Bus Read Timing

 $(Vcc = +5.0 V\pm 10\%, Fc = 10 MHz, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin name	Condition	Value (10 MHz)	Unit	Remarks	
Parameter	Symbol	Pin name	Condition	Min.	Max.	Unit	Remarks	
$\begin{array}{c} \text{Valid address} \rightarrow \overline{\text{RD}} \downarrow \\ \text{time} \end{array}$	tavrl	RD, A15 to A08, AD7 to AD0		1/4 t _{inst} * – 64 ns	_	ns		
RD pulse width	t rlrh	RD		1/2 tinst* – 20 ns	_	ns		
Valid address → data read time	tavdv	AD7 to AD0, A15 to A08		_	1/2 tinst*	ns	No wait	
$\overline{RD} \downarrow \to data \ read \ time$	tRLDV	RD, AD7 to AD0		_	1/2 tinst* – 80 ns	ns	No wait	
$\overline{RD} \uparrow \to data \; hold \; time$	t RHDX	AD7 to AD0, RD	Load	0	_	ns		
$\overline{RD} \uparrow \to ALE \uparrow time$	t RHLH	RD, ALE	condition:	1/4 tinst* – 40 ns	_	ns		
$\overline{\text{RD}} \uparrow \rightarrow \text{address invalid time}$	t rhax	RD, A15 to A08	50 pF	1/4 tinst* – 40 ns	_	ns		
$\overline{RD} \downarrow \to CLK \uparrow time$	t RLCH	RD, CLK		1/4 tinst* - 60 ns	_	ns		
$CLK \downarrow \rightarrow \overline{RD} \uparrow time$	tclrh	RD, CLK		0	_	ns		
$\overline{RD} \downarrow \to BUFC \downarrow time$	t RLBL	RD, BUFC		- 5	_	ns		
BUFC ↑ → valid address time	t BHAV	A15 to A08, AD7 to AD0, BUFC		5	_	ns		

*: For information on tinst, see "(4) Instruction Cycle."

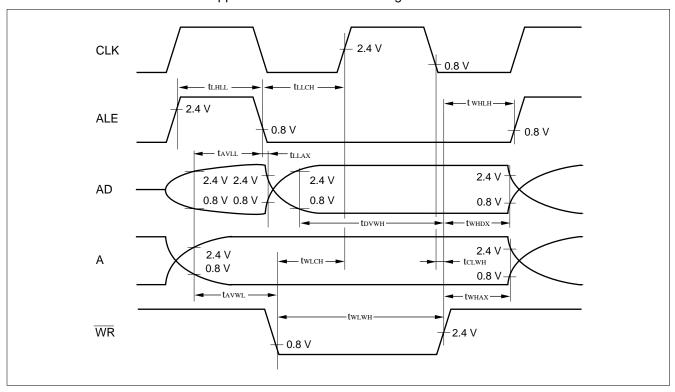


(7) Bus Write Timing

 $(Vcc = +5.0 V\pm 10\%, Fc = 10 MHz, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Domenication	Comple of	Din nama	0	Value (1	0 MHz)	11:4	Damania
Parameter	Symbol	Pin name	Condition	Min.	Max.	Unit	Remarks
Valid address \rightarrow ALE \downarrow time	tavll	AD7 to AD0,		1/4 t _{inst} *1 – 64 ns	_	ns	
ALE \downarrow time \rightarrow address invalid time	tLLAX	ALE, A15 to A08		5	_	ns	
Valid address → $\overline{\text{WR}} \downarrow \text{time}$	t avwl	WR, ALE		1/4 tinst*1 – 60 ns	_	ns	
WR pulse width	twlwh	WR		1/2 t _{inst*1} – 20 ns	_	ns	
Write data \rightarrow \overline{WR} \uparrow time	t DVWH	AD7 to AD0, WR	1 1	1/2 t _{inst*1} – 60 ns	_	ns	
$\overline{\mathrm{WR}} \uparrow \rightarrow \mathrm{address} \; \mathrm{invalid} \; \mathrm{time}$	twhax	WR, A15 to A08	Load condition: 50 pF	1/4 t _{inst} *1 – 40 ns	_	ns	
$\overline{WR} \uparrow \to data \; hold \; time$	twhox	AD7 to AD0, WR		1/4 t _{inst} *1 – 40 ns	_	ns	
$\overline{WR} \uparrow \to ALE \uparrow time$	twhlh	WR, ALE		1/4 t _{inst} *1 – 40 ns	_	ns	
$\overline{WR} \downarrow \to CLK \uparrow time$	twlch	WD CLK		1/4 t _{inst} *1 – 60 ns	_	ns	
$CLK \downarrow \rightarrow \overline{WR} \uparrow time$	tclwh	WR, CLK		0	_	ns	
ALE pulse width	t LHLL	ALE		txcyl - 35 ns*2	_	ns	
$ALE \downarrow \rightarrow CLK \uparrow time$	t LLCH	ALE, CLK		txcyL - 35 ns*2	_	ns	

- *1: For information on tinst, see "(4) Instruction Cycle."
- *2: These characteristics are also applicable to the bus read timing.

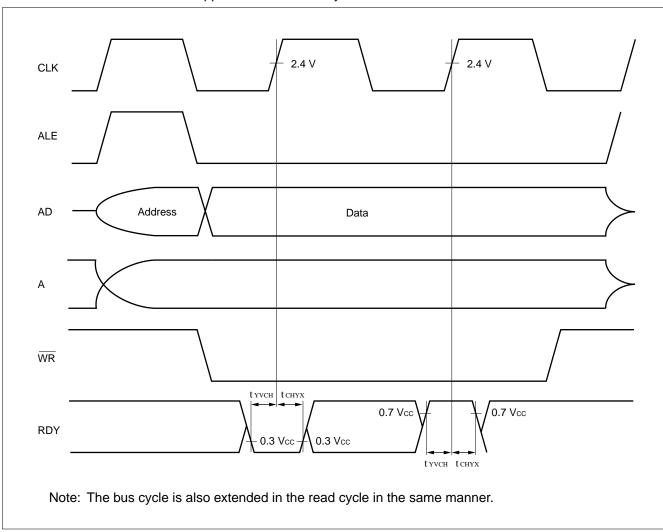


(8) Ready Input Timing

 $(Vcc = +5.0 V\pm 10\%, Fc = 10 MHz, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin name	Condition	Va	lue	Unit	Remarks
	Syllibol	Fill Hallie	Condition	Min.	Max.		Remarks
RDY valid \rightarrow CLK \uparrow time	tүүсн	RDY,	Load condition:	60	_	ns	*
$CLK \uparrow \to RDY$ invalid time	t chyx	CLK	50 pF	0	_	ns	*

*: These characteristics are also applicable to the read cycle.

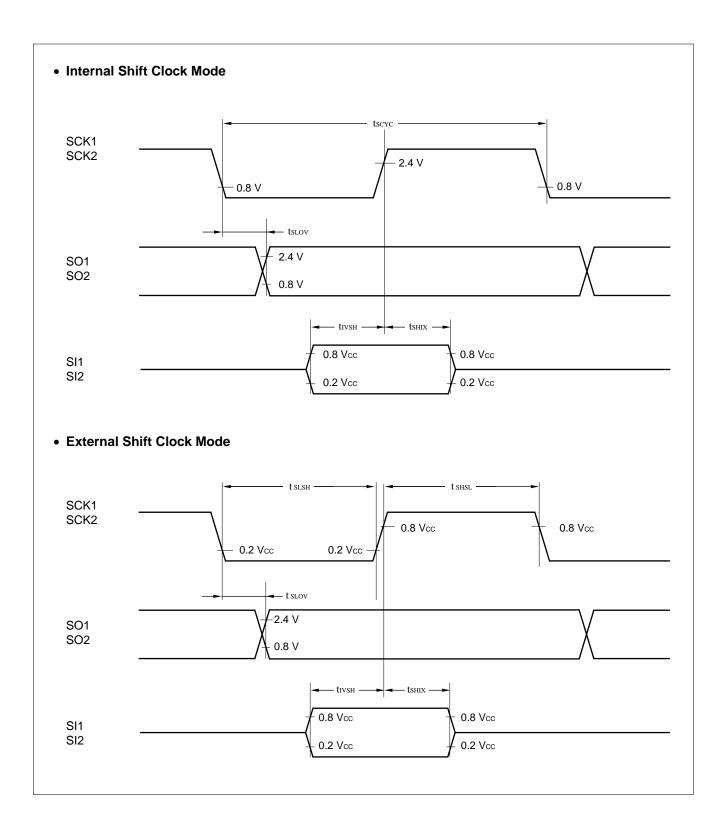


(9) UART and Serial I/O Timing

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Doromotor	Symbol	Din nama	Condition	Val	ue	l lni4	Domorko
Parameter	Symbol	Pin name	Condition	Min.	Max.	Unit	Remarks
Serial clock cycle time	tscyc	SCK1,SCK2		2 tinst*	_	μs	
$\begin{array}{c} SCK1 \downarrow \to SO1 \ time \\ SCK2 \downarrow \to SO2 \ time \end{array}$	tsLOV	SCK1, SO1 SCK2, SO2	Internal shift clock mode Load condition: 50 pF	-200	200	ns	
Valid SI1 → SCK1 ↑ Valid SI2 → SCK2 ↑	tıvsн	SI1, SCK1 SI2, SCK2		1/2 t inst*	_	μs	
$\begin{array}{c} SCK1 \uparrow \longrightarrow valid \; SI1 \; hold \; time \\ SCK2 \uparrow \longrightarrow valid \; SI2 \; hold \; time \end{array}$	t shix	SCK1, SI1 SCK2, SI2		1/2 t inst*	_	μs	
Serial clock "H" pulse width	t shsl	SCK1, SCK2		1 tinst*	_	μs	
Serial clock "L" pulse width	t slsh	SUNT, SUNZ	External	1 tinst*	_	μs	
$\begin{array}{c} SCK1 \downarrow \to SO1 \ time \\ SCK2 \downarrow \to SO2 \ time \end{array}$	tsLOV	SCK1, SO1 SCK2, SO2	shift clock mode	0	200	ns	
Valid SI1 → SCK1 ↑ Valid SI2 → SCK2 ↑	t ivsH	SI1, SCK1 SI2, SCK2	Load condition: 50 pF	1/2 t inst*	_	μs	
$\begin{array}{c} SCK1 \uparrow \to valid \; SI1 \; hold \; time \\ SCK2 \uparrow \to valid \; SI2 \; hold \; time \end{array}$	t sнıx	SCK1, SI1 SCK2, SI2	1	1/2 t _{inst} *	_	μs	

^{*:} For information on tinst, see "(4) Instruction Cycle."

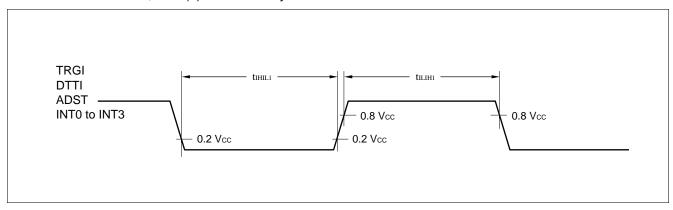


(10) Peripheral Input Timing

 $(Vcc = +5.0 V\pm 10\%, AVss = Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin name	Condition	Va	lue	Unit	Remarks
	Symbol	Finitianie	Condition	Min.	Max.		iveillai ks
Peripheral input "H" pulse width 1	tılıH1	TRGI, DTTI, ADST, INT0 to INT3	Load condition: 50 pF	2 tinst*	_	μs	
Peripheral input "L" pulse width 1	t _{IHIL1}			2 tinst*	ı	μs	

^{*:} For information on tinst, see "(4) Instruction Cycle."



5. A/D Converter Electrical Characteristics

 $(AVcc = Vcc = +3.5 \text{ V to } +6.0 \text{ V}, Fc = 10 \text{ MHz}, AVss = Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min.	Тур.	Max.	Unit	Remarks
Resolution	_		AVcc = Vcc	_	_	10	bit	
Linearity error				_	_	±2.0	LSB	
Differential linearity error				_	_	±1.5	LSB	
Total error				_	_	±3.0	LSB	
Zero transition voltage	Vот	AN0 to AN7		AVss – 1.5	AVss + 0.5	AVss + 2.5	LSB	
Full-scale transition voltage	VFST			AVR – 3.5	AVR – 1.5	AVR + 0.5	LSB	
Interchannel disparity	_	_		_	_	4	LSB	
A/D mode conversion time			_	_	33 tinst*	_	μs	
Analog port input current	lain	AN0 to AN7	_	_	_	10	μΑ	
Analog input voltage			_	0	_	AVR	V	
Reference voltage	-	AVR	_	0	_	AVcc	V	
Reference voltage supply current	IR		AVR = 5.0 V	_	200	_	μΑ	

^{*:} For information on tinst, see "(4) Instruction Cycle" in "4. AC Characteristics."

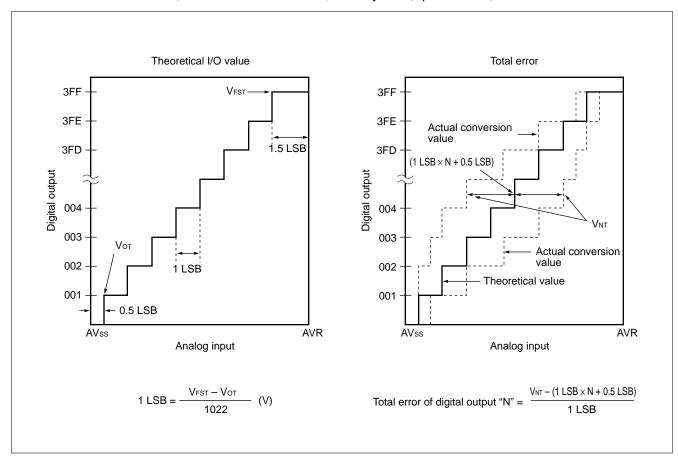
6. A/D Converter Glossary

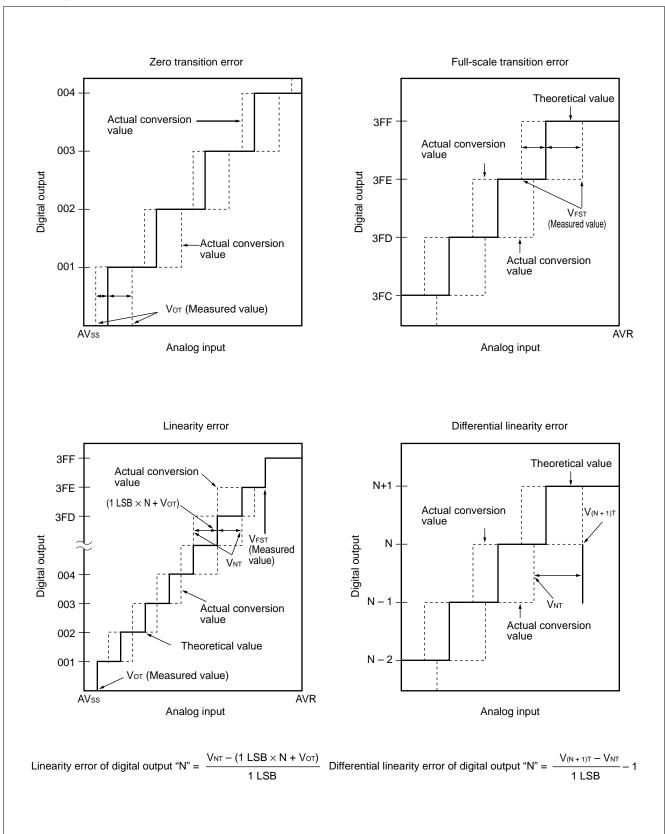
- Resolution
 - Analog changes that are identifiable with the A/D converter
- Linearity error

The deviation of the straight line connecting the zero transition point ("00 0000 0000" \leftrightarrow "00 0000 0001") with the full-scale transition point ("11 1111 1111" \leftrightarrow "11 1111 1110") from actual conversion characteristics

- · Differential linearity error
 - The deviation of input voltage needed to change the output code by 1 LSB from the theoretical value
- Total error

The total error indicates the difference between the actual value and theoretical value. This error is caused by the zero transition error, full-scale transition error, linearity error, quantization, and noise.





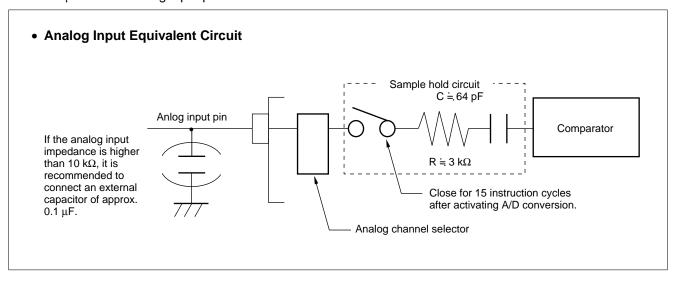
7. Notes on Using A/D Converter

. Input impedance of the analog input pins

The A/D converter used for the MB89860/850 series contains a sample hold circuit as illustrated below to fetch analog input voltage into the sample hold capacitor for fifteen instruction cycles after activation A/D conversion.

For this reason, if the output impedance of the external circuit for the analog input is high, analog input voltage might not stabilize within the analog input sampling period. Therefore, it is recommended to keep the output impedance of the external circuit low (below 10 k Ω).

Note that if the impedance connot be kept low, it is recommended to connect an external capacitor of about $0.1 \mu F$ for the analog input pin.

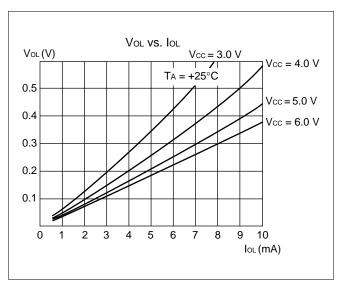


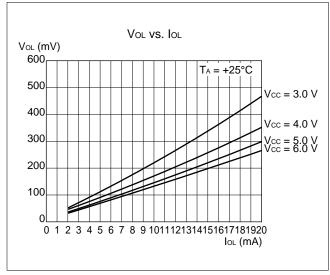
• Error

The smaller the | AVR - AVss |, the greater the error would become relatively.

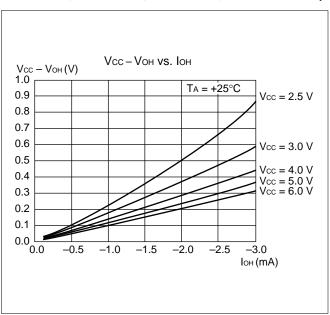
■ EXAMPLE CHARACTERISTICS

- (1) "L" Level Output Voltage (P00 to P07, P10 to P17, P20 to P27, P30 to P37, and P50 to P57)
- (2) "L" Level Output Voltage (P40 to P47)

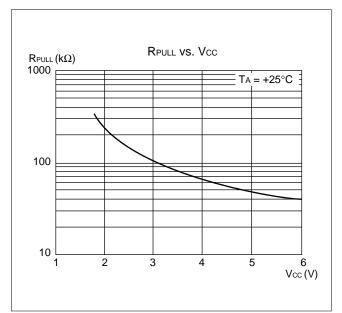




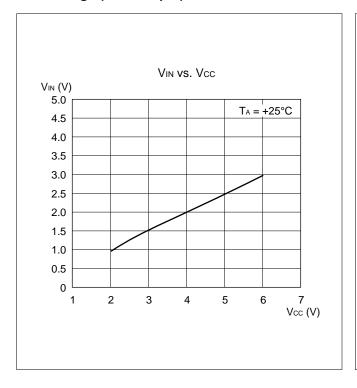
(3) "H" Level Output Voltage (P00 to P07, P10 to P17, P20 to P27, P30 to P37, and P40 to P47)



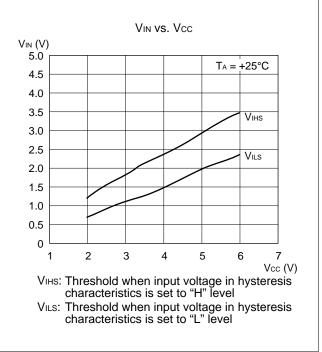
(4) Pull-up Resistance



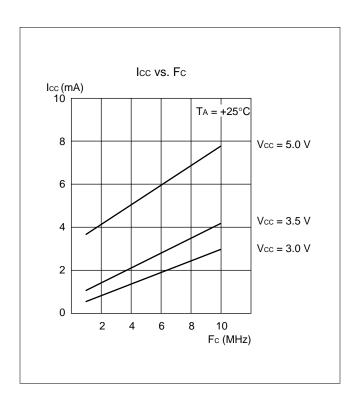
(5) "H" Level Input Voltage/"L" Level Input Voltage (CMOS Input)



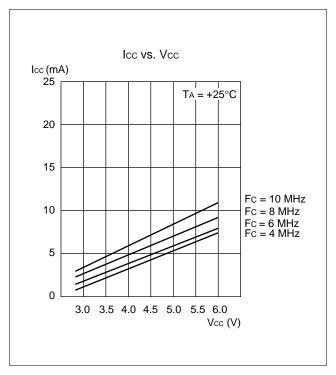
(6) "H" Level Input Voltage/"L" level Input Voltage (Hysteresis Input)



(7) Operating Supply Current vs. Frequency

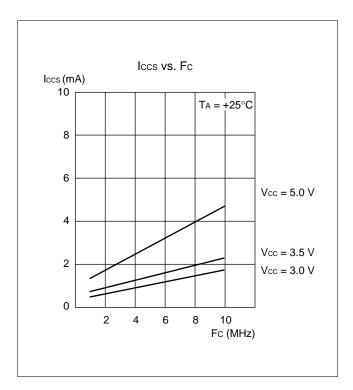


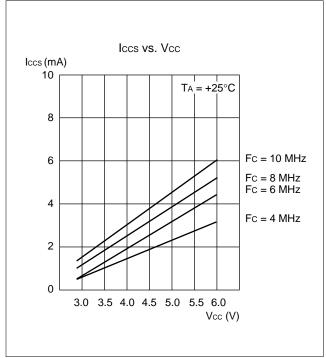
(8) Operating Supply Current vs. Vcc



(9) Sleep Power Supply Current vs. Frequency

(10) Sleep Power Supply Current vs. Vcc





■ INSTRUCTIONS

Execution instructions can be divided into the following four groups:

- Transfer
- Arithmetic operation
- Branch
- Others

Table 1 lists symbols used for notation of instructions.

Table 1 Instruction Symbols

Symbol	Meaning
dir	Direct address (8 bits)
off	Offset (8 bits)
ext	Extended address (16 bits)
#vct	Vector table number (3 bits)
#d8	Immediate data (8 bits)
#d16	Immediate data (16 bits)
dir: b	Bit direct address (8:3 bits)
rel	Branch relative address (8 bits)
@	Register indirect (Example: @A, @IX, @EP)
А	Accumulator A (Whether its length is 8 or 16 bits is determined by the instruction in use.)
AH	Upper 8 bits of accumulator A (8 bits)
AL	Lower 8 bits of accumulator A (8 bits)
Т	Temporary accumulator T (Whether its length is 8 or 16 bits is determined by the instruction in use.)
TH	Upper 8 bits of temporary accumulator T (8 bits)
TL	Lower 8 bits of temporary accumulator T (8 bits)
IX	Index register IX (16 bits)

(Continued)

(Continued)

Symbol	Meaning
EP	Extra pointer EP (16 bits)
PC	Program counter PC (16 bits)
SP	Stack pointer SP (16 bits)
PS	Program status PS (16 bits)
dr	Accumulator A or index register IX (16 bits)
CCR	Condition code register CCR (8 bits)
RP	Register bank pointer RP (5 bits)
Ri	General-purpose register Ri (8 bits, i = 0 to 7)
×	Indicates that the very \times is the immediate data. (Whether its length is 8 or 16 bits is determined by the instruction in use.)
(×)	Indicates that the contents of \times is the target of accessing. (Whether its length is 8 or 16 bits is determined by the instruction in use.)
((×))	The address indicated by the contents of \times is the target of accessing. (Whether its length is 8 or 16 bits is determined by the instruction in use.)

Columns indicate the following:

Mnemonic: Assembler notation of an instruction

~: Number of instructions

#: Number of bytes

Operation: Operation of an instruction

TL, TH, AH: A content change when each of the TL, TH, and AH instructions is executed. Symbols in

the column indicate the following:

• "-" indicates no change.

• dH is the 8 upper bits of operation description data.

• AL and AH must become the contents of AL and AH immediately before the instruction

is executed.

• 00 becomes 00.

N, Z, V, C: An instruction of which the corresponding flag will change. If + is written in this column,

the relevant instruction will change its corresponding flag.

OP code: Code of an instruction. If an instruction is more than one code, it is written according to

the following rule:

Example: 48 to 4F \leftarrow This indicates 48, 49, ... 4F.

Table 2 Transfer Instructions (48 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
MOV dir,A	3	2	$(dir) \leftarrow (A)$	_	_	_		45
MOV @IX +off,A	4	2	$((IX) + off) \leftarrow (A)$	_	_	–		46
MOV ext,A	4	3	$(ext) \leftarrow (A)$	_	_	_		61
MOV @EP,A	3	1	((EP)) ← (A)	_	_	_		47
MOV Ri,A	3	1	$(Ri) \leftarrow (A)$	_	_	_		48 to 4F
MOV A,#d8	2	2	(A) ← d8	AL	_	_	++	04
MOV A,dir	3	2	$(A) \leftarrow (dir)$	AL	_	_	++	05
MOV A,@IX +off	4	2	$(A) \leftarrow ((IX) + off)$	AL	_	_	++	06
MOV A,ext	4	3	$(A) \leftarrow (ext)$	AL	_	_	++	60
MOV A,@A	3	1	$(A) \leftarrow (A)$	AL	_	_	++	92
MOV A,@EP	3	1	$(A) \leftarrow ((EP))$	AL	_	_	++	07
MOV A,Ri	3	1	$(A) \leftarrow (Ri)$	AL	_	_	++	08 to 0F
MOV dir,#d8	4	3	$(dir) \leftarrow d8$	_	_	_		85
MOV @IX +off,#d8	5	3	((IX) +off) ← d8	_	_	_		86
MOV @EP,#d8	4	2	((EP)) ← d8	_	_	_		87
MOV GLI,#d8	4	2	$(Ri) \leftarrow d8$	_	_	_		88 to 8F
MOVW dir,A	4	2	$(dir) \leftarrow do$ $(dir) \leftarrow (AH), (dir + 1) \leftarrow (AL)$	_	_	_		D5
MOVW @IX +off,A	5	2	$((IX) + off) \leftarrow (AH),$	_	_	_		D6
INOVVV @IX +OII,A	5		$((1X) + 011) \leftarrow (A11),$ $((1X) + 0ff + 1) \leftarrow (AL)$	_	_	_		
MOVAN aut A	_	_						
MOVW ext,A	5	3	$(\text{ext}) \leftarrow (\text{AH}), (\text{ext} + 1) \leftarrow (\text{AL})$	_	-	_		D4
MOVW @EP,A	4	1	$((EP)) \leftarrow (AH), ((EP) + 1) \leftarrow (AL)$	_	_	_		D7
MOVW EP,A	2	1	(EP) ← (A)	_		- .		E3
MOVW A,#d16	3	3	(A) ← d16	AL	AH	dH	++	E4
MOVW A,dir	4	2	$(AH) \leftarrow (dir), (AL) \leftarrow (dir + 1)$	AL	AH	dH	++	C5
MOVW A,@IX +off	5	2	$(AH) \leftarrow ((IX) + off),$	AL	AH	dH	++	C6
1	_	_	$(AL) \leftarrow ((IX) + off + 1)$					
MOVW A,ext	5	3	$(AH) \leftarrow (ext), (AL) \leftarrow (ext + 1)$	AL	AH	dH	++	C4
MOVW A,@A	4	1	$(AH) \leftarrow (\ (A)\),\ (AL) \leftarrow (\ (A)\) + 1)$	AL	AH	dH	++	93
MOVW A,@EP	4	1	$(AH) \leftarrow ((EP)), (AL) \leftarrow ((EP) + 1)$	AL	AH	dH	++	C7
MOVW A,EP	2	1	$(A) \leftarrow (EP)$	_	–	dH		F3
MOVW EP,#d16	3	3	(EP) ← d16	_	–	-		E7
MOVW IX,A	2	1	$(IX) \leftarrow (A)$	_	_	_		E2
MOVW A,IX	2	1	$(A) \leftarrow (IX)$	_	_	dH		F2
MOVW SP,A	2	1	$(\hat{SP}) \leftarrow (\hat{A})$	_	_	_		E1
MOVW A,SP	2	1	$(A) \leftarrow (SP)$	_	_	dH		F1
MOV @A,T	3	1	$(A) \leftarrow (T)$	_	_	_		82
MOVW @A,T	4	1	$((A)) \leftarrow (TH), ((A) + 1) \leftarrow (TL)$	_	_	_		83
MOVW IX,#d16	3	3	(IX) ← d16	_	_	_		E6
MOVW A,PS	2	1	$(A) \leftarrow (PS)$	_	_	dH		70
MOVW PS,A	2	1	(PS) ← (A)	_	_	_	++++	71
MOVW SP,#d16	3	3	(SP) ← d16	_	_	_		E5
SWAP	2	1	$(AH) \leftrightarrow (AL)$	_	_	AL		10
SETB dir: b	4	2	(dir) : b \leftarrow 1	_	_	'_		A8 to AF
CLRB dir: b	4	2	(dir): $b \leftarrow 0$	_	_	_		A0 to A7
XCH A,T	2	1	$(AL) \leftrightarrow (TL)$	AL				42
XCHW A,T	3	1	$(AL) \leftrightarrow (TL)$ $(A) \leftrightarrow (T)$	AL	AH	dH		43
	3	1				dH		F7
XCHW A,EP	3		$(A) \leftrightarrow (EP)$	_	_	dH		l .
XCHW A,IX			$(A) \leftrightarrow (IX)$	_	_	_		F6
XCHW A,SP	3	1	$(A) \leftrightarrow (SP)$	_	_	dH		F5
MOVW A,PC	2	1	(A) ← (PC)	_	_	dH		F0

Notes: • During byte transfer to A, T ← A is restricted to low bytes.
• Operands in more than one operand instruction must be stored in the order in which their mnemonics are written. (Reverse arrangement of F²MC-8 family)

Table 3 Arithmetic Operation Instructions (62 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
ADDC A,Ri	3	1	$(A) \leftarrow (A) + (Ri) + C$	_	_	_	++++	28 to 2F
ADDC A,#d8	2	2	$(A) \leftarrow (A) + d8 + C$	_	_	_	++++	24
ADDC A,dir	3	2	$(A) \leftarrow (A) + (dir) + C$	-	-	_	++++	25
ADDC A,@IX +off	4	2	$(A) \leftarrow (A) + ((IX) + off) + C$	-	-	_	++++	26
ADDC A,@EP	3	1	$(A) \leftarrow (A) + ((EP)) + C$	_	_	_	++++	27
ADDCW A	3	1	$(A) \leftarrow (A) + (T) + C$	_	_	dH	++++	23
ADDC A	2	1	$(AL) \leftarrow (AL) + (TL) + C$	_	_	_	++++	22
SUBC A,Ri	3	1	$(A) \leftarrow (A) - (Ri) - C$	_	_	_	++++	38 to 3F
SUBC A,#d8	2	2	$(A) \leftarrow (A) - d8 - C$	_	_	_	++++	34
SUBC A,dir	3	2	$(A) \leftarrow (A) - (dir) - C$	_	_	_	++++	35
SUBC A,@IX +off	4	2	$(A) \leftarrow (A) - ((IX) + off) - C$	_	_	_	++++	36
SUBC A,@EP	3	1	$(A) \leftarrow (A) - ((EP)) - C$	_	_	_	++++	37
SUBCW A	3	1	$(A) \leftarrow (T) - (A) - C$	_	-	dH	++++	33
SUBC A	2	1	$(AL) \leftarrow (TL) - (AL) - C$	_	_	_	++++	32
INC Ri	4	1	(Ri) ← (Ri) + 1	_	-	_	+++-	C8 to CF
INCW EP	3	1	(EP) ← (EP) + 1	–	–	_		C3
INCW IX	3	1	$(IX) \leftarrow (IX) + 1$	_	-	_		C2
INCW A	3	1	$(A) \leftarrow (A) + 1$	_	_	dΗ	++	C0
DEC Ri	4	1	$(Ri) \leftarrow (Ri) - 1$	_	_	_	+++-	D8 toDF
DECW EP	3	1	$(EP) \leftarrow (EP) - 1$	_	_	_		D3
DECW IX	3	1	$(IX) \leftarrow (IX) - 1$	_	_	_		D2
DECW A	3	1	$(A) \leftarrow (A) - 1$	_	_	dH	++	D0
MULU A	19	1	$(A) \leftarrow (AL) \times (TL)$	_	_	dH		01
DIVU A	21	1	$(A) \leftarrow (T) / (AL), MOD \rightarrow (T)$	dL	00	00		11
ANDW A	3	1	$(A) \leftarrow (A) \land (T)$	_	_	dΗ	++R-	63
ORW A	3	1	$(A) \leftarrow (A) \lor (T)$	_	_	dΗ	++R-	73
XORW A	3	1	$(A) \leftarrow (A) \forall (T)$	_	_	dΗ	++R-	53
CMP A	2	1	(TL) – (AL)	_	_	_	++++	12
CMPW A	3	1	(T) - (A)	_	_	_	++++	13
RORC A	2	1	\rightarrow C \rightarrow A \rightarrow	_	_	_	++-+	03
ROLC A	2	1		_	_	_	++-+	02
CMP A,#d8	2	2	(A) – d8	_	_	_	++++	14
CMP A,dir	3	2	(A) – (dir)	_	_	_	++++	15
CMP A,@EP	3	1	(A) – ((EP))	_	_	_	++++	17
CMP A,@IX +off	4	2	(A) - (IX) + off)	_	_	_	++++	16
CMP A,Ri	3	1	(A) – (Ri)	_	_	_	++++	18 to 1F
DAA	2	1	Decimal adjust for addition	_	_	_	++++	84
DAS	2	i	Decimal adjust for subtraction	_	_	_	++++	94
XOR A	2	i	$(A) \leftarrow (AL) \forall (TL)$	_	_	_	++R-	52
XOR A,#d8	2	2	$(A) \leftarrow (AL) \forall d8$	_	_	_	++R-	54
XOR A,dir	3	2	$(A) \leftarrow (AL) \forall (dir)$	_	_	_	++R-	55
XOR A,@EP	3	1	$(A) \leftarrow (AL) \forall (EP)$	_	_	_	++R-	57
XOR A,@IX +off	4	2	$(A) \leftarrow (AL) \lor ((IX) + off)$	_	_	_	++R-	56
XOR A,Ri	3	1	$(A) \leftarrow (AL) \lor (AX) + O(A)$ $(A) \leftarrow (AL) \lor (Ri)$	_		_	++R-	58 to 5F
AND A	2	1	$(A) \leftarrow (AL) \lor (RI)$ $(A) \leftarrow (AL) \land (TL)$	_		_	++R-	62
AND A,#d8	2	2	$(A) \leftarrow (AL) \wedge (1L)$ $(A) \leftarrow (AL) \wedge d8$	_		_	++R-	64
AND A,#do	3	2	$(A) \leftarrow (AL) \wedge dS$ $(A) \leftarrow (AL) \wedge (dir)$	_	_	_	++R-	65
AND A, all	J		(AL) A (All)	_			++K-	03

(Continued)

(Continued)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
AND A,@EP	3	1	$(A) \leftarrow (AL) \land ((EP))$	_	_	_	++R-	67
AND A,@IX +off	4	2	$(A) \leftarrow (AL) \land ((IX) + off)$	_	_	_	+ + R –	66
AND A,Ri	3	1	$(A) \leftarrow (AL) \land (Ri)$	_	_	_	+ + R –	68 to 6F
OR A	2	1	$(A) \leftarrow (AL) \lor (TL)$	_	_	_	+ + R –	72
OR A,#d8	2	2	$(A) \leftarrow (AL) \lor d8$	_	_	_	+ + R –	74
OR A,dir	3	2	$(A) \leftarrow (AL) \lor (dir)$	_	_	_	+ + R –	75
OR A,@EP	3	1	$(A) \leftarrow (AL) \lor ((EP))$	_	_	_	+ + R –	77
OR A,@IX +off	4	2	$(A) \leftarrow (AL) \lor ((IX) + off)$	_	_	_	+ + R –	76
OR A,Ri	3	1	$(A) \leftarrow (AL) \lor (Ri)$	_	_	_	+ + R –	78 to 7F
CMP dir,#d8	5	3	(dir) – d8	_	_	_	++++	95
CMP @EP,#d8	4	2	((ÉP)) – d8	_	_	_	++++	97
CMP @IX +off,#d8	5	3	((IX) +off) – d8	_	_	_	++++	96
CMP Ri,#d8	4	2	(Ri) – d8	_	_	_	++++	98 to 9F
INCW SP	3	1	(SP) ← (SP) + 1	_	_	_		C1
DECW SP	3	1	(SP) ← (SP) – 1	_	_	_		D1

Table 4 Branch Instructions (17 instructions)

Mnemonic	~	#	Operation	TL	TH	АН	NZVC	OP code
BZ/BEQ rel	3	2	If Z = 1 then PC ← PC + rel	_	_	_		FD
BNZ/BNE rel	3	2	If $Z = 0$ then $PC \leftarrow PC + rel$	_	_	_		FC
BC/BLO rel	3	2	If C = 1 then PC ← PC + rel	_	_	_		F9
BNC/BHS rel	3	2	If C = 0 then PC ← PC + rel	_	_	_		F8
BN rel	3	2	If N = 1 then PC ← PC + rel	_	_	_		FB
BP rel	3	2	If N = 0 then PC ← PC + rel	_	_	_		FA
BLT rel	3	2	If $V \forall N = 1$ then $PC \leftarrow PC + rel$	_	_	_		FF
BGE rel	3	2	If $V \forall N = 0$ then $PC \leftarrow PC + rel$	_	_	_		FE
BBC dir: b,rel	5	3	If (dir: b) = 0 then $PC \leftarrow PC + rel$	_	_	_	-+	B0 to B7
BBS dir: b,rel	5	3	If (dir: b) = 1 then PC \leftarrow PC + rel	_	_	_	-+	B8 to BF
JMP @A	2	1	$(PC) \leftarrow (A)$	_	_	_		E0
JMP ext	3	3	(PC) ← ext	_	_	_		21
CALLV #vct	6	1	Vector call	_	_	_		E8 to EF
CALL ext	6	3	Subroutine call	_	_	_		31
XCHW A,PC	3	1	$(PC) \leftarrow (A),(A) \leftarrow (PC) + 1$	_	_	dΗ		F4
RET	4	1	Return from subrountine	_	_	_		20
RETI	6	1	Return form interrupt	_	_	_	Restore	30

Table 5 Other Instructions (9 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
PUSHW A	4	1		_	_	_		40
POPW A	4	1		_	_	dΗ		50
PUSHW IX	4	1		_	_	_		41
POPW IX	4	1		_	_	_		51
NOP	1	1		_	_	_		00
CLRC	1	1		_	_	_	R	81
SETC	1	1		_	_	_	S	91
CLRI	1	1		_	_	_		80
SETI	1	1		_	_	_		90

■ INSTRUCTION MAP

1		U		×	<u> </u>	U	۵	×	۵	<u>le</u>	re	<u>e</u>	<u>a</u>	<u>e</u>	<u>e</u>	<u>a</u>	<u>a</u>
NOP SYMP RET RET PUSHW POPW MOV MOVM CLM SET CLM BEC MOV DECW MOV MOV CLM SET CLM BEC MOV DECW MOV MOV CLM SET CLM BEC MOV DECW MOV MOV CLM SET CLM SET MOV DECW MOV MOV CLM SET MOV MOV MOV MOV MOV CLM SET MOV M	ш	MOVW A,PC	MOVW A,SP	MOVW A,IX	MOVW A,EP												
MOP SIMP RET RETT PUSHW POPW MOW CLRT SETT CLRB BBC MOW DECWN MOW CLRP SET SETT SET	ш		MOWV SP,A	MOWV IX,A	MOVW EP,A	MOVW A,#d16	MOVW SP#d16	MOVW IX,#d16	MOVW EP#d16								CALLV #7
MOP SYMP RET RETT PUSHW POPW MOV MOWW CLRR SETT CLRB BEC MOV MOWW CLRC SETC SETC	۵		DECW		DECW	MOVW ext,A	MOVW dir,A	MOWW @IX +d,A	MOWW @EP,A								DEC R7
MOP SWAP RET RETI PUSHW POPW MOV MOW CLRR SET CLRB B	ပ	l	l			MOVW A,ext	MOVW A,dir	MOVW A,@IX +d	MOVW A,@EP								INC R7
MOD	В	BBC dir: 0,rel	BBC dir: 1,rel	BBC dir: 2,rel	BBC dir: 3,rel	BBC dir: 4,rel	BBC dir:5,rel	BBC dir: 6,rel	BBC dir: 7,rel	BBS dir: 0,rel	BBS dir: 1,rel	BBS dir: 2,rel	BBS dir: 3,rel	BBS dir: 4,rel	BBS dir:5,rel	BBS dir:6,rel	BBS dir:7,rel
NOP SWAP RET RETI PUSHWI POPW MOV MOVW CLRG SE	⋖	CLRB dir: 0	CLRB dlr: 1	CLRE	CLRE	CLRB dir: 4	CLRB dlr:5	CLRB dlr: 6	CLRB dlr: 7	SETE	SETE	SETE	SETE	SETE	SETE	SETE	
NOP SWAP RET RETI	6	SETI	SETC	MO	MOM	DAS	8		CMP @EP#d8	5	S	5	5	5	5	중	
NOP SWAP RET RETI PUSHW POPW MOV MUU	∞	CLRI	CLRC	MOV @A,T	MOVW @A,T		MOV dir,#d8	MOV @IX+d,#d8		MOV R0,#d8	MOV R1,#d8	MOV R2,#d8	MOV R3,#d8	MOV R4,#d8	MOV R5,#d8	MOV R6,#d8	MOV R7,#d8
MOV SWAP RET RETI PUSHW POPW MOV MULU DINU JIMP CALL PUSHW POPW MOV ROLC CMP ADDC SUBC XCH XOR AND ROLC CMP ADDC SUBC XCH XOR AND ROLC CMP ADDC SUBC XCH XOR AND ROLC CMP ADDC SUBC MOV XOR AND MOV CMP ARE AR	^	MOWW A,PS	MOWW PS,A			용		OR A,@IX +d	OR A,@EP								OR A,R7
NOP SWAP RET RETI PUSHW PO	9					AND A,#d8	I	AND A,@IX +d	AND A,@EP				AND A,R3		AND A,R5	AND A,R6	AND A,R7
NOP SWAP RET RETI PUSI	2		l			XOR A,#d8	XOR A,dir	XOR A,@IX +d	XOR A,@EP	XOR A,R0	XOR A,R1	XOR A,R2	XOR A,R3	XOR A,R4	XOR A,R5	XOR A,R6	XOR A,R7
NOP SWAP RET RE	4	PUSHW A	PUSHW	XCH	XCHW A, T		_	MOV @IX +d,A	ĭ	MOV	MOV R1,A		MOV	_		MOV R6,A	MOV R7,A
NOP SWAP RE	က	RETI	ა		SUBCW	SUE	SUB(SUBC A,@IX +d	S	SUB	SUBC A,R1	SUB	SUB	SUB	SUB	SUB(
MOV CI CI CI CI CI CI CI C	2	RET	1	ADDC	ADDCW	ADL	ADD(ADDC A,@IX +d	A[ADD	ADD	ADD	ADD	ADD	ADD	ADD	
H MON	-	SWAP	DNIQ	CMP	CMPW	CM	CMP	CMP A,@IX +d	5	CMP	CMP A,R1	CMP	CMP	CMP	CMP	CMP	
T	0	NOP				MOV A,#d8		MOV A,@IX +d	MOV A,@EP	MOV A,R0	MOV A,R1	MOV A,R2	MOV A,R3		MOV A,R5		MOV A,R7
	H	0	_	7	က	4	2	9	7	8	6	⋖	ω	ပ	٥	ш	Щ

■ MASK OPTIONS (MB89855R)

Option type	Option selection	Remarks
Power-on reset	0: Without power-on reset 1: With power-on reset	_
Initial value of oscillation stabilization delay time	0: 2 ¹⁸ /Fc (s) (Crystal oscillator) 1: 2 ¹⁴ /Fc (s) (Ceramic oscillator)	Selects the initial value of the OSCS bit in the STBC register during power-on reset.
Reset pin output	0: Without reset output 1: With reset output	_
Pull-up resistor at port pin P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P60 to P64	1: Without pull-up resistor 0: With pull-up resistor	 Can be set per pin. P00 to P07, P10 to P17, and P20 to P27 with a pull-up resistor can be set only for single-chip mode.

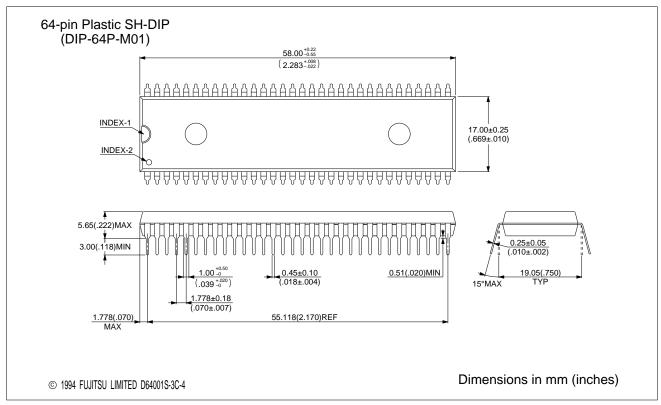
■ STANDARD OPTION LIST

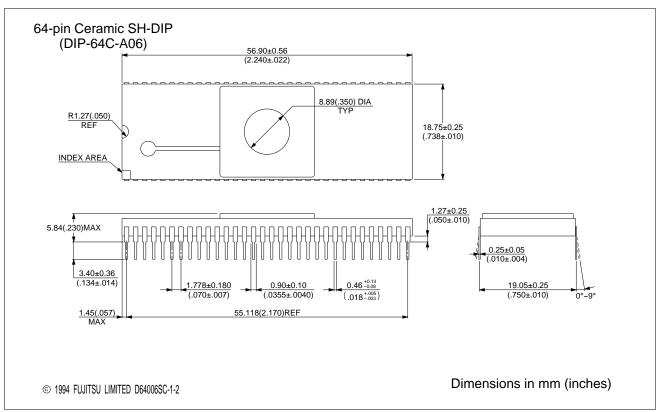
Part number Parameter	MB89P857/W857
Power-on reset	Available
Initial value of oscillation stabilization delay time	2 ¹⁸ /Fc (s)
Output at reset pin	Available
Pull-up resistor at port pin	Not available

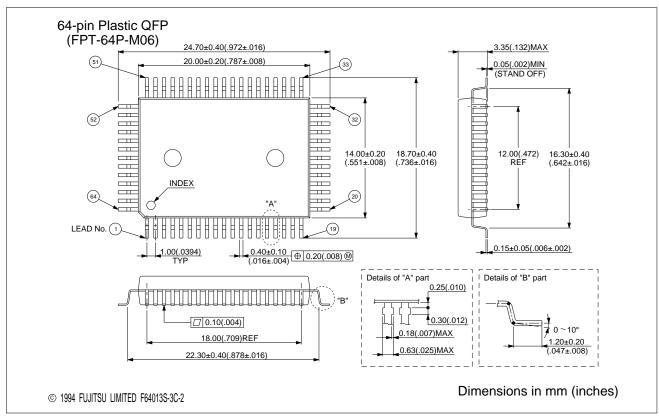
■ ORDERING INFORMATION

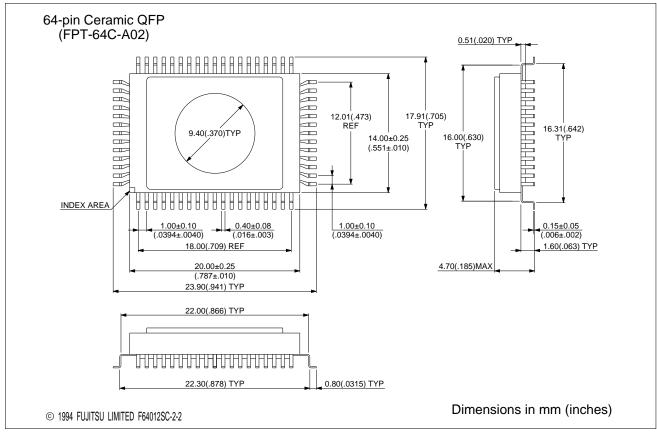
Part number	Package	Remarks
MB89855RP-SH MB89P857P-SH	64-pin Plastic SH-DIP (DIP-64P-M01)	
MB89W857C-SH	64-pin Ceramic SH-DIP (DIP-64C-A06)	ES level only
MB89W857CF-ES-BND	64-pin Ceramic QFP (FPT-64C-A02)	ES level only

■ PACKAGE DIMENSIONS









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